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7823

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re Application of:  
Ken Chen

Confirmation Number: 4186

Serial No.: 10/058,473

Group Art Unit: 2823

Examiner: TOLEDO, FERNANDO

Filed: 01/28/2002

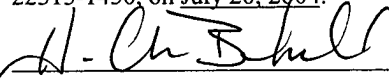
TKHR Docket No. 252016-1040

Top-Team Ref. 0503-A30594US

For: **ENHANCED ADHESION STRENGTH BETWEEN MOLD RESIN AND  
POLYIMIDE**

**Certificate of Mailing**

I hereby certify that this correspondence is being deposited with  
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Commissioner for Patents, P.O. Box 1450, Alexandria, VA  
22313-1450, on July 20, 2004.

  
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Signature – Hui Chin Barnhill

**AMENDMENT AND RESPONSE TO OFFICE ACTION**

Mail Stop –Amendment  
Assistant Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

The Office Action mailed April 20, 2004 has been carefully considered. In response  
thereto, please enter the following amendments and consider the following remarks.